

SB160R 1.0AMP. SCHOTTKY BARRIER RECTIFIERS DO-41 FEATURE . High current capability . Low forward voltage drop . Low power loss, high efficiency 1.0(25.4).107(2.7) . High surge capability DIA. MIN. 080(2. High temperature soldering guaranteed 260°C /10sec/ 0.375" lead length at 5 lbs tension .205(5.2)**MECHANICAL DATA** .166(4.2). Terminal: Plated axial leads solderable per 032(0.8)DIA. MIL-STD 202E, method 208C 1.0(25.4).025(0.65)MIN. . Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy (free halogen) . Polarity: color band denotes cathode . Mounting position: any Dimensions in inches and (millimeters) **MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS** Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20% SYM **SB160R Type Number** units BOL Maximum Recurrent Peak Reverse Voltage $V_{\rm RRM}$ 60 V **V**_{RMS} 42 V Maximum RMS Voltage Maximum DC blocking Voltage 60 V $V_{\rm DC}$ Maximum Average Forward Rectified Current 1.0 А I_{F(AV)} .375''(9.5mm) lead length at T_L = 90°C Peak Forward Surge Current 8.3ms single half sine- wave superimposed on rated load (JEDEC IFSM 30.0 A method) Maximum Forward Voltage at 1.0A DC $V_{\rm F}$ 0.70 V Maximum DC Reverse Current $@T_A = 25^{\circ}C$ 0.1 $I_{\rm R}$ mА 10.0 at rated DC blocking voltage $(a)T_A = 100^{\circ}C$ $C_{\rm J}$ 110 Typical Junction Capacitance (Note1) pF Typical Thermal Resistance (Note2) 50 ℃/W $R_{(JA)}$ °C Temperature Storage **T**STG -55 to +150 -55 to +150 °C **Operating Junction Temperature** TJ

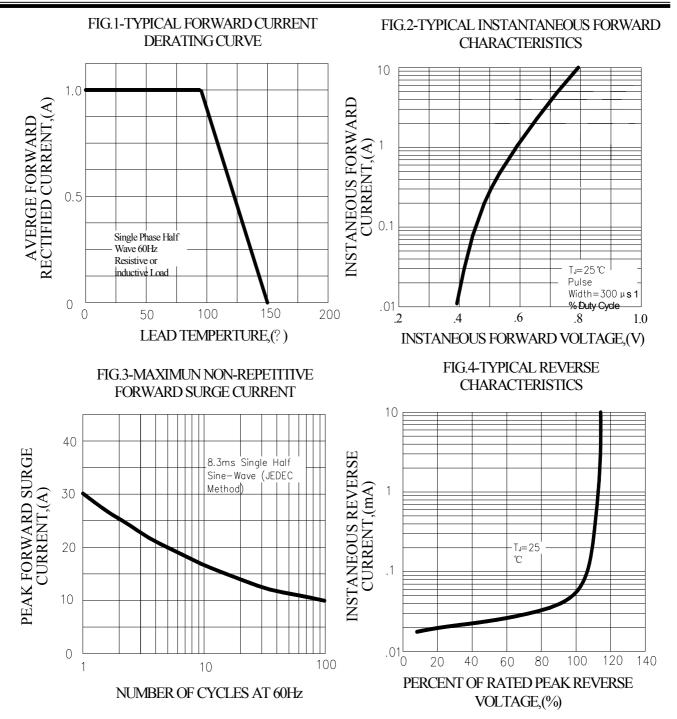
Note:

1. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc

2. Thermal Resistance from Junction to Ambient at 0.375"(9.5mm)lead length, vertical P.C.Board Mounted



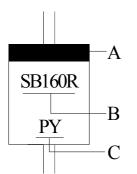
RATING AND CHARACTERISTIC CURVES (SB160R)





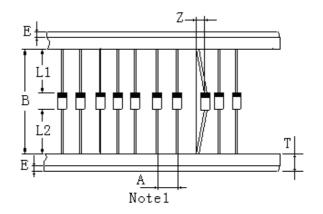
Marking and packaging illustration

1. Marking



SYMBOL	Explanation	
Α	Color Band Denotes Cathode	
B	Product Name	
С	Trademark	

2、Packaging



ITEM	SYMBOL	SPECIFICATIONS	SPECIFICATIONS	
		(mm)	(inch)	
Component alignment	Ζ	1.2max	0.048max	
Tape width	Т	5.0±0.4	0.2±0.016	
Exposed adhesive	Е	0.8max	0.032max	
Body eccentricity	L1-L2	1.0max	0.040max	
Component	А	5.0±0.5	0.2±0.02	
Inner tap	В	52.0~53.5	2.06~2.11	
NOTE:			•	
Each component lead shall be sandwiched between tapes for a minimum of 2.5mm (0.1inch)				